

**SLOVENSKI STANDARD****SIST EN 60249-2-1:1997****01-avgust-1997**

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**Base materials for printed circuits - Part 2: Specifications - Specification No.1: Phenolic cellulose paper copper-clad laminated sheet, high electrical quality (IEC 249-2-1:1985 + A1:1989)**

Base materials for printed circuits -- Part 2: Specifications - Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet, high electrical quality

Basismaterialien für gedruckte Schaltungen -- Teil 2: Einzelbestimmungen - Einzelbestimmung Nr. 1: Kupferkaschierte Phenolharz-Hartpapiertafeln, hohe elektrische Qualität

Matériaux de base pour circuits imprimés -- Partie 2: Spécifications - Spécification n° 1: Feuille de papier cellulose phénolique recouverte de cuivre de haute qualité électrique

**Ta slovenski standard je istoveten z: EN 60249-2-1:1994**

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**ICS:**

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards plošče

**SIST EN 60249-2-1:1997**

**en**

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EUROPEAN STANDARD

EN 60249-2-1

NORME EUROPEENNE

EUROPÄISCHE NORM

January 1994

UDC 621.3.049.75-036

Supersedes HD 313.2.1 S2:1990

Descriptors: Printed board, base material, specification, phenolic paper

## ENGLISH VERSION

Base materials for printed circuits  
 Part 2: Specifications  
 Specification No. 1: Phenolic cellulose paper  
 copper-clad laminated sheet, high electrical  
 quality  
 (IEC 249-2-1:1985 + A1:1989)

Matériaux de base pour circuits  
 imprimés  
 Partie 2: Spécifications  
 Spécification n° 1: Feuille de  
 papier cellulose phénolique  
 recouverte de cuivre de haute  
 qualité électrique  
 (CEI 249-2-1:1985 + A1:1989)

Basismaterialien für gedruckte  
 Schaltungen  
 Teil 2: Einzelbestimmungen  
 Einzelbestimmung Nr. 1:  
 Kupferkaschierte  
 Phenolharz-Hartpapiertafeln,  
 hohe elektrische Qualität  
 (IEC 249-2-1:1985 + A1:1989)

This European Standard was approved by CENELEC on 1993-12-08.  
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 a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards  
 may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German).  
 A version in any other language made by translation under the responsibility of  
 a CENELEC member into its own language and notified to the Central Secretariat  
 has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium,  
 Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg,  
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CENELEC

European Committee for Electrotechnical Standardization  
 Comité Européen de Normalisation Electrotechnique  
 Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

FOREWORD

At the request of CENELEC 74th Technical Board, HD 313.2.1 S2:1990 (IEC 249-2-1:1985 + A1:1989) was submitted to the CENELEC voting procedure for conversion into a European Standard.

The text of the International Standard was approved by CENELEC as EN 60249-2-1 on 8 December 1993.

The following dates were fixed:

- latest date of publication of an identical national standard (dop) 1995-03-15
- latest date of withdrawal of conflicting national standards (dow) -

Annexes designated "normative" are part of the body of the standard. In this standard, annex ZA is normative.

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The text of the International Standard IEC 249-2-1:1985 and its amendment 1:1989 was approved by CENELEC as a European Standard without any modification.

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## ANNEX ZA (normative)

OTHER INTERNATIONAL PUBLICATIONS QUOTED IN THIS STANDARD  
WITH THE REFERENCES OF THE RELEVANT EUROPEAN PUBLICATIONS

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies.

NOTE : When the international publication has been modified by CENELEC common modifications, indicated by (mod), the relevant EN/HD applies.

IEC Publication	Date	Title	EN/HD	Date
249-1	1982	Base materials for printed circuits Part 1: Test methods	EN 60249-1*	1993
249-3A	1976	Part 3: Special materials used in connection with printed circuits - First supplement: Specification No. 2: Specification for copper foil for use in the manufacture of copper-clad base materials	-	-

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<https://standards.iteh.ai/catalog/standards/sist/4d260d7d-a7a0-472c-81c1-7d06f652ac61/sist-en-60249-2-1-1997>

\* EN 60249-1 includes A1:1984 + A2:1989 + A3:1991 to IEC 249-1

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COMMISSION ÉLECTROTECHNIQUE INTERNATIONALE  
NORME DE LA CEI

INTERNATIONAL ELECTROTECHNICAL COMMISSION  
IEC STANDARD

Publication 249-2-1

Deuxième édition — Second edition

1985

Matériaux de base pour circuits imprimés

Deuxième partie: Spécifications

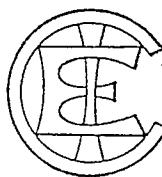
Spécification n° 1: Feuille de papier cellulose phénolique recouverte de cuivre  
de haute qualité électrique

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Base materials for printed circuits

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Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet,  
high electrical quality



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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## BASE MATERIALS FOR PRINTED CIRCUITS

## Part 2: Specifications

Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet,  
high electrical quality

## FOREWORD

- 1) The formal decisions or agreements of the IEC on technical matters, prepared by Technical Committees on which all the National Committees having a special interest therein are represented, express, as nearly as possible, an international consensus of opinion on the subjects dealt with.
- 2) They have the form of recommendations for international use and they are accepted by the National Committees in that sense.
- 3) In order to promote international unification, the IEC expresses the wish that all National Committees should adopt the text of the IEC recommendation for their national rules in so far as national conditions will permit. Any divergence between the IEC recommendation and the corresponding national rules should, as far as possible, be clearly indicated in the latter.
- 4) The IEC has not laid down any procedure concerning marking as an indication of approval and has no responsibility when an item of equipment is declared to comply with one of its recommendations.

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## PREFACE

SIST EN 60249-2-1:1997

This standard has been prepared by IEC Technical Committee No. 52: Printed Circuits.

This second edition replaces the first edition of Specification No. 1 which was included in IEC Publication 249-2.

This standard forms Specification No. 1 of a publication series which will replace the specifications originally included in IEC Publication 249-2 and will also include new specifications.

The text of this standard is based on the following documents:

Six Months' Rule	Reports on Voting
52(CO)236	52(CO)265 and 265A

Further information can be found in the Reports on Voting, indicated in the table above.

*The following IEC publications are quoted in this standard:*

Publications Nos. 249-1 (1982): Base Materials for Printed Circuits, Part 1: Test Methods.  
249-3A (1976): First Supplement to Publication 249-3 (1973): Metal-clad Base Materials for Printed Circuits. Part 3: Special Materials Used in Connection with Printed Circuits — Specification No. 2: Specification for Copper Foil for Use in the Manufacture of Copper-clad Base Materials.

## BASE MATERIALS FOR PRINTED CIRCUITS

### Part 2: Specifications

#### Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet, high electrical quality

##### 1. Scope

This specification gives requirements for properties of phenolic cellulose paper copper-clad laminated sheet, high electrical quality, in thicknesses of 0.5 mm up to 6.4 mm.

*Note.* — To designate this material, the reference: 249-2-1-IEC-PF-CP-Cu may be used; if there is no risk of confusion, the type designation may be abbreviated to read IEC-249-2-1.

##### 2. Materials and construction

The sheet consists of an insulating base with metal foil bonded to one or both sides.

###### 2.1 Insulating base

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Phenolic resin bonded cellulose paper laminate.  
(standards.iteh.ai)

###### 2.2 Metal foil

Copper as specified in IEC Publication 249-3A: First Supplement to Publication 249-3: Metal-clad Base Materials for Printed Circuits, Part 3: Special Materials Used in Connection with Printed Circuits — Specification No. 2: Specification for Copper Foil for Use in the Manufacture of Copper-clad Base Materials.

The preferred foils are Type A (electro-deposited copper) of standard ductility.

##### 3. Internal marking

Each sheet should bear a manufacturer's identification mark that is:

- in black or some other colour not to be confused with red (red colour shall not be used as this indicates a material of defined flammability);
- repeated at intervals so that no part of the sheet is further than 75 mm (3 in) from the furthest point of the nearest mark;
- printed so as to indicate the machine direction of the filling material; if letters or numbers are used, these shall be upright in the machine direction.

Examples:

A	A	A	A	A
A	A	A	A	A
A	A	A	A	A
A	A	A	A	A
A	A	A	A	A

↑  
machine direction

12	12	12	12	12
12	12	12	12	12
12	12	12	12	12
12	12	12	12	12
12	12	12	12	12

## 4. Electrical properties

TABLE I

Property	Test method (Sub-clause of IEC Publication 249-1) *	Requirement
Resistance of foil	2.1	As specified in IEC Publication 249-3A
Surface resistance while in the humidity chamber (optional)	2.2	1 000 MΩ min.
Surface resistance after recovery	2.2	10 000 MΩ min.
Volume resistivity while in the humidity chamber (optional)	2.3	100 MΩm min.
Volume resistivity after recovery	2.3	1 000 MΩm min.
Surface corrosion	2.4	No visible corrosion products in the gap
Corrosion at the edge	2.5	Positive pole: not worse than A/B Negative pole: not worse than 1.6
Relative permittivity after damp heat and recovery	SIST EN 2.70249-2-1:1997 <a href="https://standards.itehai/catalog/standards/sist/4d260d7d-a5.50-472c-81c1-7d06f652ac61/sist-en-60249-2-1-1997">https://standards.itehai/catalog/standards/sist/4d260d7d-a5.50-472c-81c1-7d06f652ac61/sist-en-60249-2-1-1997</a>	The average value shall not exceed 5.50-472c-81c1-7d06f652ac61/sist-en-60249-2-1-1997
Dielectric dissipation factor after damp heat and recovery	2.7	The average value shall not exceed 0.05
Surface resistance at 100 °C	2.9.1	100 MΩ min.
Volume resistivity at 100 °C	2.9.1	100 MΩm min.

\* Base Materials for Printed Circuits, Part 1: Test methods.

## 5. Non-electrical properties of the copper-clad sheet

## 5.1 Appearance of the copper-clad face

## 5.1.1 Normal surface finish

The copper-clad face shall be substantially free from blisters, wrinkles, pinholes, deep scratches, pits and resin. Any discoloration or contamination shall be readily removable with a hydrochloric acid solution of density 1.02 g/cm<sup>3</sup> or with a suitable organic solvent.

## 5.1.2 High-quality surface finish (optional)

If a surface of high quality is essential for precious metal plating or fine line etching and is ordered by the purchaser the following requirements shall apply in addition to those of Sub-clause 5.1.1 when inspected in accordance with Sub-clause 3.9 of IEC Publication 249-1.